## CLAIMS

- 1. An organic thin film transistor comprising: an organic substrate;
- a gate electrode;
- 5 a gate insulating film;
  - an organic semiconductor film;
  - a source electrode; and
  - a drain electrode,

wherein an average surface roughness Ra of the 10 gate electrode which is in contact with the gate insulating film is 0.1 nm to 15 nm.

- 2. The organic thin film transistor according to claim 1, wherein the organic substrate is made of one of a glass epoxy resin and polyethylene terephthalate.
- 3. The organic thin fi

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- 3. The organic thin film transistor according to claim 1, wherein the organic substrate is made of polyimide.
- 4. A method of manufacturing an organic thin film transistor comprising an organic substrate, a gate electrode, a gate insulating film, an organic semiconductor film, a source electrode, and a drain electrode, the method comprising the step of:

preparing an organic substrate in which a

25 planarized gate electrode is formed on a surface thereof; and

forming a gate insulating film on the

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wherein an average surface roughness Ra of the planarized gate electrode is 0.1 nm to 15 nm.

- 5. The method of manufacturing an organic thin film transistor according to claim 4, wherein the organic substrate is made of one of a glass epoxy resin and polyethylene terephthalate.
- 6. The method of manufacturing an organic thin film transistor according to claim 4, wherein the organic substrate is made of polyimide.
- 7. The method of manufacturing an organic thin film transistor according to claim 4, wherein the planarized gate electrode is formed by sputtering.
- 8. The method of manufacturing an organic thin
  film transistor according to claim 4, further
  comprising planarizing the gate electrode.
- The method of manufacturing an organic thin film transistor according to claim 8, wherein in planarizing, at least one of chemical mechanical
   polishing (CMP), soft etching, and polishing tape processing is performed.